PMP10081 REV C Bill of Materials

Designator	Quantity	Value	PartNumber	Manufacturer	Description	PackageReference
C1	1	330pF	GRM188R71H331KA01D	MuRata	CAP, CERM, 330pF, 50V, +/-10%, X7R, 0603	0603
C2	1	0.22uF	GRM188R71E224KA88D	MuRata	CAP, CERM, 0.22uF, 25V, +/-10%, X7R, 0603	0603
C3, C19	2	1000pF	GRM188R71H102KA01D	MuRata	CAP, CERM, 1000pF, 50V, +/-10%, X7R, 0603	0603
C4, C6, C7, C20	4	0.1uF	GRM188R71H104KA93D	MuRata	CAP, CERM, 0.1 µF, 50 V, +/- 10%, X7R, 0603	0603
C5	1	220uF	EEE-FK1H221GP	Panasonic	CAP, AL, 220uF, 50V, +/-20%, 0.18 ohm, SMD	SMT Radial G
C8	1	1uF	GRM21BR71H105KA12L	MuRata	CAP, CERM, 1uF, 50V, +/-10%, X7R, 0805	0805
C9	1	100pF	06033C101KAT2A	AVX	CAP, CERM, 100pF, 25V, +/-10%, X7R, 0603	0603
C10	1	1uF	GRM188R71E105KA12D	MuRata	CAP, CERM, 1uF, 25V, +/-10%, X7R, 0603	0603
C11, C12, C13, C14	4	10uF	GRM32ER71H106KA12L	MuRata	CAP, CERM, 10uF, 50V, +/-10%, X7R, 1210	1210
C15	1	330uF	25SVPF330M	Panasonic	CAP, Polymer, 330 µF, 25 V, +/- 20%, 0.014 ohm, F12, SMD, 2-Leads, Body 10.5x10.5mm, Height 12.7mm SMD	F12, SMD, 2-Leads, Body 10.5x10.5mm, Height 12.7mm
C16, C18	2	22uF	GRM32ER71E226KE15L	MuRata	CAP, CERM, 22uF, 25V, +/-10%, X7R, 1210	1210
C17	1	0.01uF	GRM188R71H103KA01D	MuRata	CAP, CERM, 0.01uF, 50V, +/-10%, X7R, 0603	0603
C21	1	0.1uF	GCM188R71H104KA57D	MuRata	CAP, CERM, 0.1uF, 50V, +/-10%, X7R, 0603	0603
D1, D2	2	6.8V	MMSZ5235BS-7-F	Diodes Inc.	Diode, Zener, 6.8V, 200mW, SOD-323	SOD-323
D3	1	60V	B560C-13-F	Diodes Inc.	Diode, Schottky, 60V, 5A, SMC	SMC
D4, D5	2	75V	BAS16-7-F	Diodes Inc.	Diode, Ultrafast, 75V, 0.3A, SOT-23	SOT-23
J1, J2	2		ED555/2DS	On-Shore Technology	Terminal Block, 6A, 3.5mm Pitch, 2-Pos, TH	7.0x8.2x6.5mm
L1	1	2.2uH	74408943022	Wurth Elektronik	Inductor, Shielded Drum Core, Ferrite, 2.2 µH, 3 A, 0.026 ohm, SMD	4.8x3.8x4.8mm
L2	1	22uH	MSD1583-223MEB	Coilcraft	Coupled inductor, 22uH, 2.44A, 0.033 ohm, +/-20%, SMD	IND_14.8x8.6x14.8mm, SMD
Q1	1	0.3V	MMBT2222A	Fairchild Semiconductor	Transistor, NPN, 40V, 0.15A, SOT-23	SOT-23
Q2	1	60V	CSD18563Q5A	Texas Instruments	MOSFET, N-CH, 60V, 15A, SON 5x6mm	SON 5x6mm
R1, R3	2	100k	CRCW0603100KFKEA	Vishay-Dale	RES, 100k ohm, 1%, 0.1W, 0603	0603
R2, R4, R19	3	20.0k	CRCW060320K0FKEA	Vishay-Dale	RES, 20.0k ohm, 1%, 0.1W, 0603	0603
R5, R8	2	10.0k	CRCW060310K0FKEA	Vishay-Dale	RES, 10.0k ohm, 1%, 0.1W, 0603	0603
R6	1	182k	CRCW0603182KFKEA	Vishay-Dale	RES, 182k ohm, 1%, 0.1W, 0603	0603
R7	1	3.92k	CRCW06033K92FKEA	Vishay-Dale	RES, 3.92k ohm, 1%, 0.1W, 0603	0603
R9, R10	2	4.64	CRCW06034R64FKEA	Vishay-Dale	RES, 4.64 ohm, 1%, 0.1W, 0603	0603
R11, R15	2	1.00k	CRCW06031K00FKEA	Vishay-Dale	RES, 1.00k ohm, 1%, 0.1W, 0603, RES, 1.00 k, 1%, 0.1 W, 0603	0603
R12	1	49.9	CRCW060349R9FKEA	Vishay-Dale	RES, 49.9 ohm, 1%, 0.1W, 0603	0603
R13, R14	2	0.025	CSRN2010FK25L0	Stackpole Electronics Inc	RES, 0.025 ohm, 1%, 1W, 2010	2010
R16	1	0	CRCW06030000Z0EA	Vishay-Dale	RES, 0, 5%, 0.1 W, 0603	0603
R17	1	2M	3224W-1-205E	Bourns	TRIMMER 2M OHM 0.25W SMD	3.5x5.3x4.8mm
R18	1	90.9k	CRCW060390K9FKEA	Vishay-Dale	RES, 90.9k ohm, 1%, 0.1W, 0603	0603

Designator	Quantity	Value	PartNumber	Manufacturer	Description	PackageReference
TP1, TP7, TP9	3	Red	5000	Keystone	Test Point, Miniature, Red, TH	Red Miniature Testpoint
TP2, TP4, TP8	3	Black	5001	Keystone	Test Point, Miniature, Black, TH	Black Miniature Testpoint
TP3	1	Orange	5003	Keystone	Test Point, Miniature, Orange, TH	Orange Miniature Testpoint
TP5, TP6	2	White	5002	Keystone	Test Point, Miniature, White, TH	White Miniature Testpoint
U1	1		TPS40210DGQR	Texas Instruments	4.5-V TO 52-V INPUT CURRENT MODE BOOST CONTROLLER, DGQ0010D	DGQ0010D
U2	1	TLC272CD	TLC272CD	TI	IC, Precision Dual Operational Amplifiers	SO8

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